

VERSION WITH MARKINGS TO SHOW CHANGES MADE

1. (Twice Amended) A semiconductor device, comprising:
a semiconductor chip;
a single dielectric layer;
electrically conductive leads on said dielectric layer; and
a low temperature curing adhesive material that cures without exceeding one hundred fifty degrees Fahrenheit, said low temperature curing adhesive material being located between said semiconductor chip and said dielectric layer.

10. (Twice Amended) [The taped semiconductor product of claim 8] A taped semiconductor product, comprising:

integrated circuits formed in semiconductor material;
a tape having openings aligned with said integrated circuits, wherein said tape includes a single dielectric layer and electrically conductive leads, said leads being printed on said single dielectric layer;
bond wires extending through said openings, said bond wires being electrically connected to said integrated circuits; and
adhesive material between said tape and said integrated circuits, wherein said adhesive material cures at room temperature.

13. (Twice Amended) A tape for manufacturing semiconductor devices, said tape comprising:

a single dielectric layer having openings;
electrically conductive leads associated with said openings, said leads being printed on said dielectric layer; and
a low temperature curing adhesive material that cures without exceeding one hundred fifty degrees Fahrenheit, said low temperature curing adhesive material being located between said semiconductor chip and said dielectric layer.